华半半导体
Huaban Semiconductor

BAP50-03

General purpose PIN diode

FEATURES

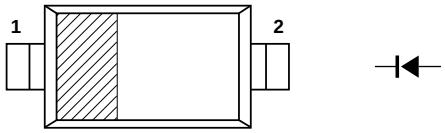
- Low diode capacitance
- Low diode forward resistance.

APPLICATIONS

- General RF applications.

DESCRIPTION

General purpose PIN diode in a SOD323 small plastic SMD package.



Marking code: A8

1 cathode
2 anode

Fig.1 Simplified outline (SOD323) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	50	V
I_F	continuous forward current		–	50	mA
P_{tot}	total power dissipation	T_s = 90 °C	–	500	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–65	+150	°C

ELECTRICAL CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	forward voltage	I_F = 50 mA	–	0.95	1.1	V
V_R	reverse voltage	I_R = 10 μA	50	–	–	V
I_R	reverse current	V_R = 50 V	–	–	100	nA
C_d	diode capacitance	V_R = 0; f = 1 MHz	–	0.4	–	pF
		V_R = 1 V; f = 1 MHz	–	0.3	0.55	pF
		V_R = 5 V; f = 1 MHz	–	0.2	0.35	pF
r_D	diode forward resistance	I_F = 0.5 mA; f = 100 MHz; note 1	–	25	40	Ω
		I_F = 1 mA; f = 100 MHz; note 1	–	14	25	Ω
		I_F = 10 mA; f = 100 MHz; note 1	–	3	5	Ω

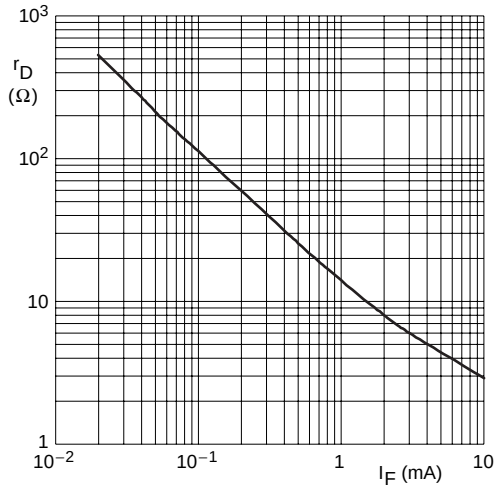
Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

THERMAL CHARACTERISTICS

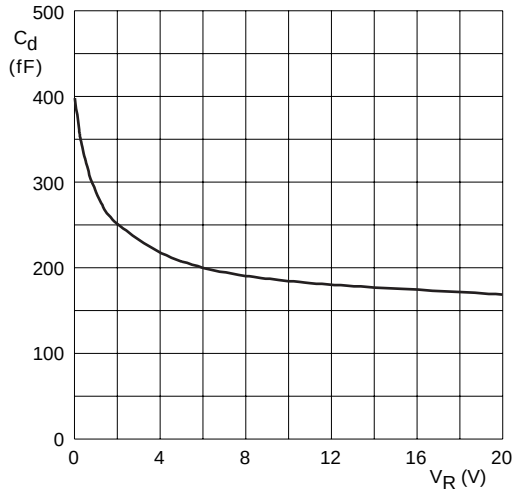
SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	85	K/W

GRAPHICAL DATA



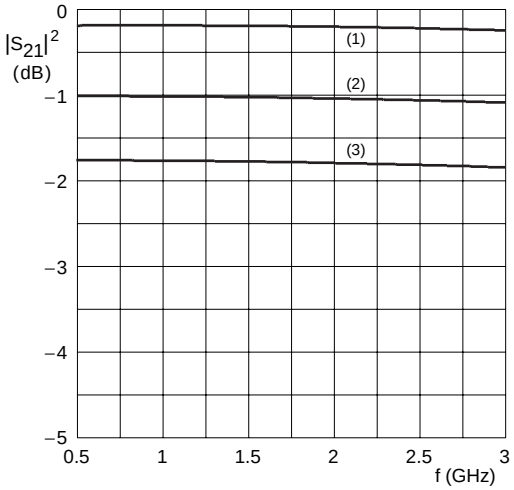
f = 100 MHz; T_j = 25 °C.

Fig.2 Forward resistance as a function of forward current; typical values.



f = 1 MHz; T_j = 25 °C.

Fig.3 Diode capacitance as a function of reverse voltage; typical values.

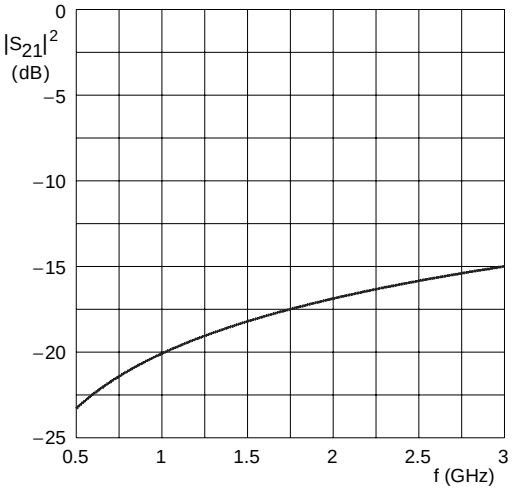


(1) I_F = 10 mA. (2) I_F = 1 mA. (3) I_F = 0.5 mA.

Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer Tee network.

T_{amb} = 25 °C.

Fig.4 Insertion loss ($|S_{21}|^2$) of the diode as a function of frequency; typical values.



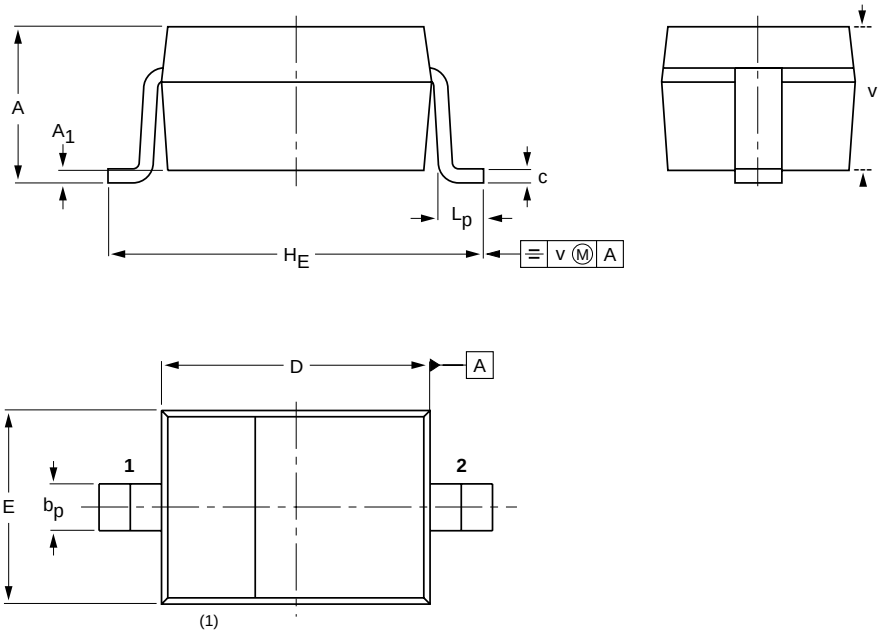
Diode zero biased and inserted in series with a 50 Ω stripline circuit.

T_{amb} = 25 °C.

Fig.5 Isolation ($|S_{21}|^2$) of the diode as a function of frequency; typical values.

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads **SOD323**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b_p	c	D	E	H_E	L_p	v	
mm	1.0 ---	0.10 – 0.00	0.35 0.25	0.15 0.08	1.8 1.6	1.40 1.20	2.7 2.5	0.40 0.25	0.90 0.80	

Note

1. The marking bar indicates the cathode.

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